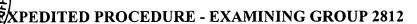
JAN 2 9 2002 💆		RCE/2812#
FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL	Application Number	09/253RECFIVED
	Filing Date	February 19, 1999
	First Named Inventor	Paul A. Farrar 2002
	Group Art Unit	ECHNOLUGY CENTER 2800
Subsection (b) of 35 U.S.C. § 132, effective on May 29, 2000, provides for continued examination of an utility or plant application filed on or after June 8, 1995.  See The American Inventors Protection Act of 1999 (AIPA)	Examiner Name	Ron Pompey
	Attorney Docket Number	303.572US1

	s a Request for Continued Examination (RCE) under 37 C.F.R. § 1.114 of the CCTIVE DEPOSITION OF SOLDER BALL CONTACTS.	the above-identified application entitled _	
Submis	ussion required under 37 C.F.R. § 1.114	F-13/RGE	
1	Consider the amendment(s)/reply under 37 C.F.R. § 1.116 previously filed	ed on $_{-}$ $1/31/62$	
2	Consider the arguments in the Appeal Brief or Reply Brief previously file	ed on _ //31/02 led on _ // Variable	
3. <u>X</u>	An Amendment Under 37 CFR § 1.116 (7 pages) is enclosed.	<b>y</b> . ·	
4	A new power of attorney (_ pages) is enclosed.		
.5. <u>X</u>	An Information Disclosure Statement is enclosed (1 page) a. 1 Form(s) 1449 b. 13 Copies of IDS Citations		
6. <u>X</u>	A check in the amount of \$740.00 is attached to pay the RCE filing fee required under C.F.R. § 1.17(e).		
7. <u>X</u>	X The Commissioner is hereby authorized to credit overpayments or charge any fees set forth in 37 C.F.R. §§ 1.16 through 1.18 to Deposit Account No. 19-0743.		
8. <u>X</u>	A petition for extension of time in the prior application (1 pages) is enclosed along with a check in the amount of \$110.00 to pay the extension fee.		
9. <u>X</u>	Other: Clean Version of Pending Claims (5 pages); Clean Version of Ar Request for Preexamination Interview (1pg).	amended Specification Paragraph (1pg):	
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)  By: Daniel J. Kluth Reg. No. 32,146			
Customer Number 21186			
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Box RCE, Washington, D.C. 20231, on this 1742 day of January, 2002.			
	A. 100	an Maint	

Signature

Name

See The American Inventors Protection Act of 1999 (AIPA).



PATENT PATENT ECHNOLOGIC

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Paul A. Farrar

Examiner: Ron Pompey

Serial No.:

09/253,611

Group Art Unit: 2812

Filed:

February 19, 1999

Docket: 303.572US1

Title:

SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

## AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.116

Box RCE Commissioner for Patents Washington, D.C. 20231

In response to the final Office Action mailed September 27, 2001, please amend the application as follows.

## IN THE SPECIFICATION

Please make the paragraph substitution indicated in the appendix entitled Clean Version of Amended Specification Paragraph. The specific change incorporated in the substitute paragraph is shown in the following marked-up version of the original paragraph:

The paragraph beginning on page 11, line 9 is amended as follows:

A still further embodiment is described with reference to Figures 4(A)-4(M) and 6(A)-6(C). In this embodiment, processing proceeds to the etching of through holes 180 to metal contact pads 150 as shown in Figure 4(M). Instead of removing the resist at this stage, a layer of lead [220] 225 is applied to the exposed portions of metal contact pads 150 through electrolysis. A layer of tin 230 is then formed on the layer of lead 225. The lead layer 225 is preferably approximately 0.91 microns deep. The tin layer 230 is preferably approximately 1.42 microns deep. The lead layer 225 and the tin layer 230 collectively form the solder contacts 200 as shown in Figure 6(A). Other metallurgies may be substituted for the lead/tin combination, and the deposition may include more than two layers.